

Title (en)

PROCESS FOR MANUFACTURING ELECTRONIC-COMPONENT PACKAGES AND ELECTRONIC-COMPONENT PACKAGE OBTAINED BY MEANS OF THIS PROCESS

Title (de)

VERFAHREN ZUR HERSTELLUNG VON ELEKTRONIKKOMPONENTENGEHÄUSEN UND DURCH DIESES VERFAHREN HERGESTELLTES ELEKTRONIKKOMPONENTENGEHÄUSE

Title (fr)

PROCÉDÉ DE FABRICATION DE BOÎTIERS DE COMPOSANT ÉLECTRONIQUE ET BOÎTIER DE COMPOSANT ÉLECTRONIQUE OBTENU PAR CE PROCÉDÉ

Publication

**EP 3821458 A1 20210519 (FR)**

Application

**EP 19749397 A 20190710**

Priority

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Abstract (en)

[origin: WO2020012120A1] The invention relates to a process for manufacturing integrated-circuit packages (110), wherein a cavity is made in a strip of dielectric material covered with a leaf of electrically conductive material. An electronic component (90) is placed in the cavity and it is encapsulated by filling the cavity at least partially with an encapsulation material (100). The bottom of the blind cavity being formed of a layer of flexible and removable material which is removed after encapsulation. The invention also relates to integrated-circuit packages (110) manufactured according to this process. These integrated-circuit packages (110) are for example QFN packages.

IPC 8 full level

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CPC (source: EP)

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Citation (search report)

See references of WO 2020012120A1

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